

30 and gold wire 32 are encapsulated in a molded encapsulant 42 using the molding process described earlier.

C/ Fig. 8 shows a second example of a molded circuit element 12 having a circuit die 30 attached to the flexible tape 10. The flexible tape 10 is a flexible material such as polyimide or the like. Via holes 41 is formed in the flexible tape 10 and copper pads 35 are formed on both sides and in the via holes 41 of the flexible tape 10. Wire bonds using a material such as gold wire 32 are bonded to the circuit die 30 and to the copper pads 35. Solder balls 36 are attached to the copper pads 35 through a solder mask 39 formed of a material not wettable by the solder. The circuit die 30 and gold wire 32 are encapsulated in a molded encapsulant 42 using the molding process described earlier.

---

In the Claims:

Please rewrite Claim 11 as follows.

11. (ONCE AMENDED) A molded flexible circuit assembly, comprising:

- a flexible tape;
  - a number of circuit die attached to said flexible tape;
  - a number of encapsulation units formed of molded encapsulation material,
- wherein each of said circuit die is covered by one of said encapsulation units; and
- a number of removable molded stiffeners formed of said molded encapsulation material.